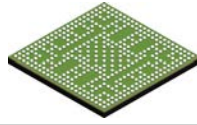


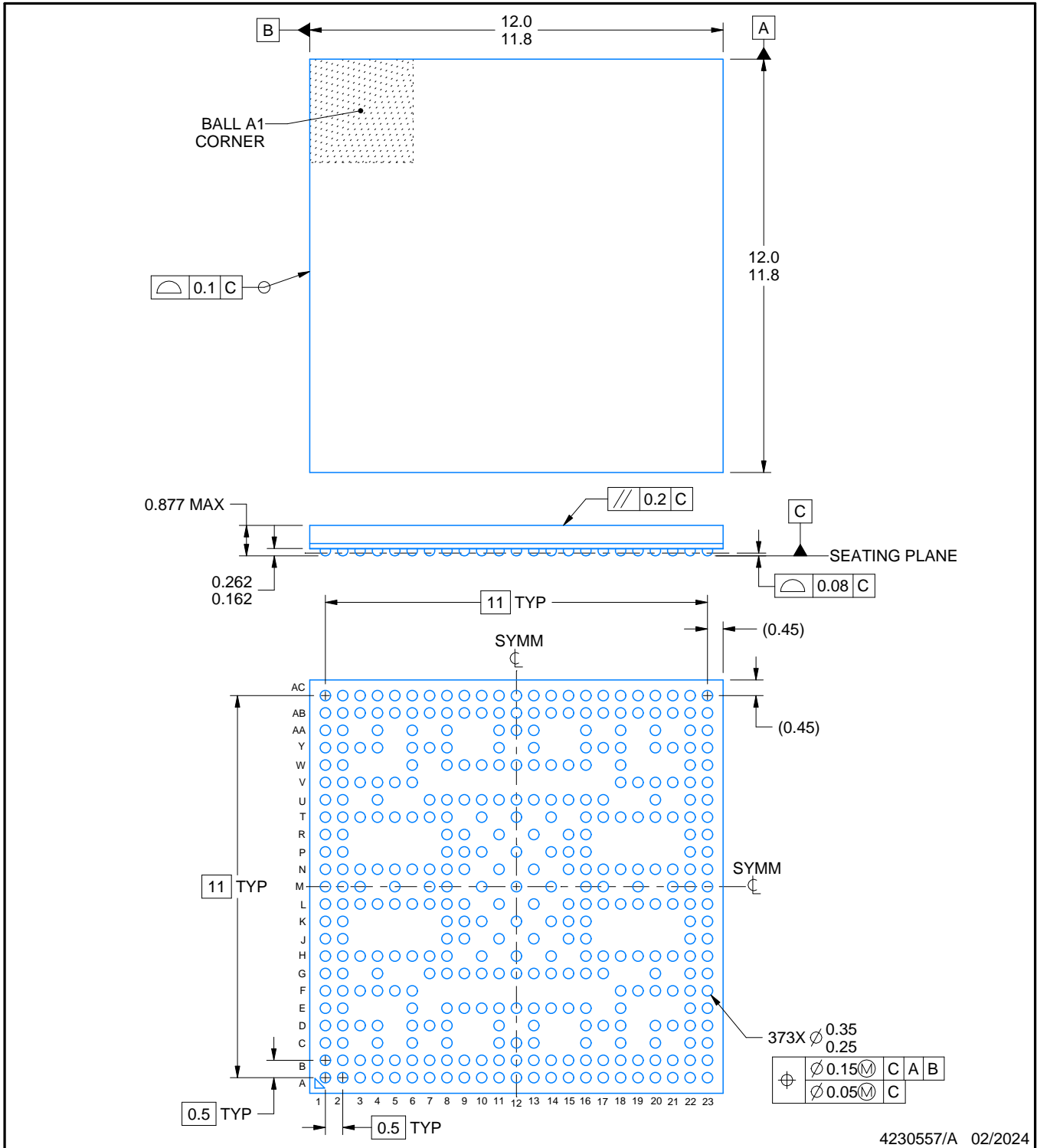
# ANB0373A



# PACKAGE OUTLINE

FCCSP - 0.877 mm max height

PLASTIC BALL GRID ARRAY



## NOTES:

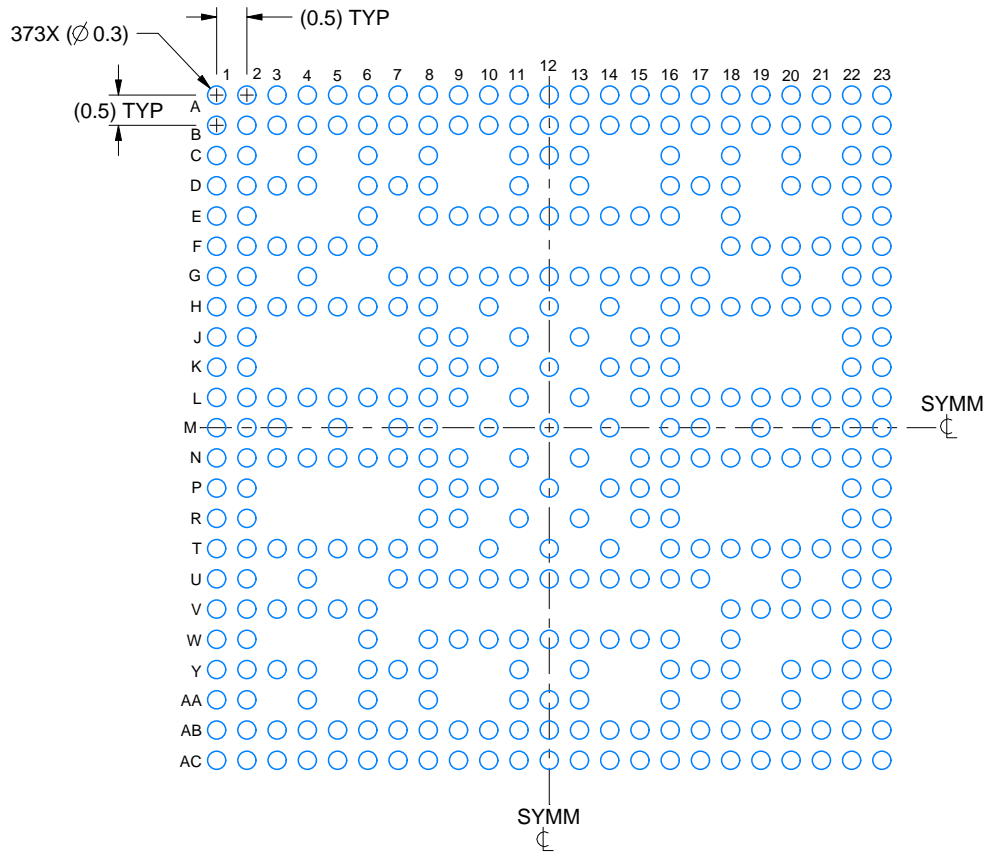
- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.

# EXAMPLE BOARD LAYOUT

ANB0373A

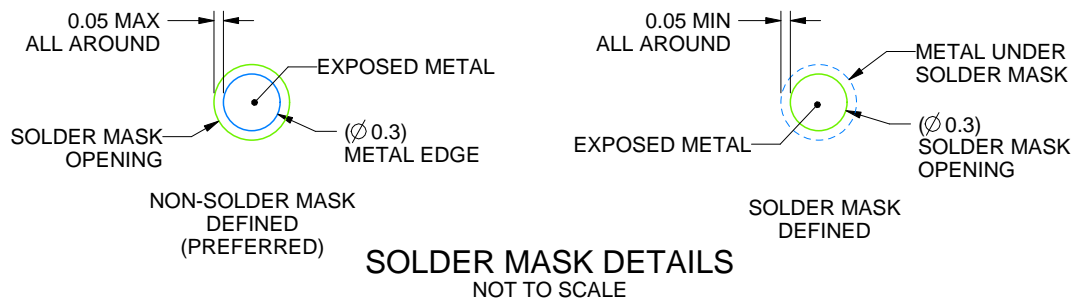
FCCSP - 0.877 mm max height

PLASTIC BALL GRID ARRAY



## LAND PATTERN EXAMPLE

EXPOSED METAL SHOWN  
SCALE: 8X



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NOTES: (continued)

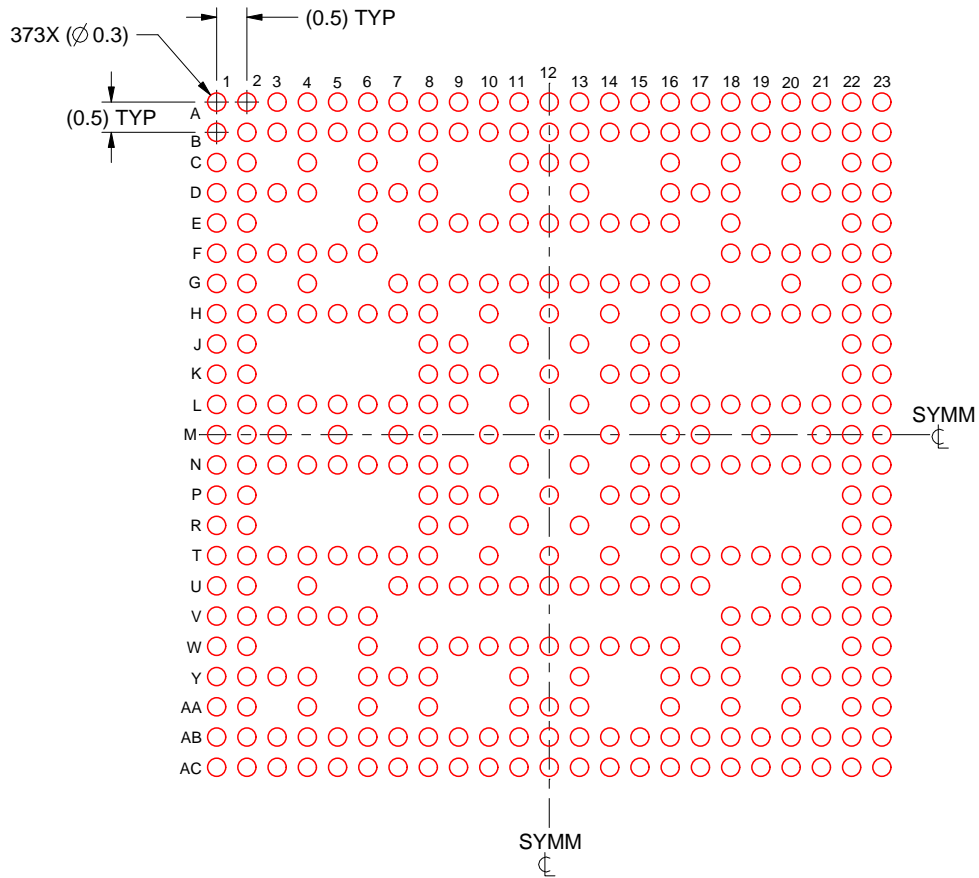
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For information, see Texas Instruments literature number SPRAA99 ([www.ti.com/lit/spraa99](http://www.ti.com/lit/spraa99)).

# EXAMPLE STENCIL DESIGN

ANB0373A

FCCSP - 0.877 mm max height

PLASTIC BALL GRID ARRAY



**SOLDER PASTE EXAMPLE**  
BASED ON 0.100 mm THICK STENCIL  
SCALE: 8X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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